

AMENDMENTS TO THE CLAIMS

Listing Of Claims

Claims 1-26 (canceled)

27. (currently amended) A semiconductor package comprising:

a substrate having a first surface and a second surface;

a semiconductor die having a first outline and a face bonded directly to the second surface;

a first mask on the first surface;

a second mask on the second surface comprising a second opening having a second outline corresponding to the first outline defining an open die attach area on the second surface;

the first mask and the second mask comprising a photoimageable material; and

~~and the second opening comprising an exposed and developed portion of the second mask; and~~

a resin encapsulating the die and covering a top surface of the second mask.

28. (previously presented) The package of claim 27 further comprising a filled adhesive layer between the face and the die attach area bonding the die to the substrate and configured to transfer heat directly from the face to the substrate.

29. (previously presented) The package of claim 27 wherein the second outline is only slightly larger than the first outline.

30. (currently amended) A semiconductor package comprising:

a substrate having a first surface, a second surface and a bonding opening there through;

a plurality of conductors on the first surface having a plurality of wire bonding pads;

a first mask on the first surface at least partially covering the conductors;

a second mask on the second surface except in a die attach area defined by an opening in the second mask;

the first mask and the second mask comprising a photoimageable material;

~~and the opening comprising an exposed and developed portion of the second mask;~~

a semiconductor die on the die attach area having a face aligned with the bonding opening attached directly to the second surface;

a filled adhesive layer attaching the face directly to the die attach area and configured to transfer heat directly from the face to the substrate;

a plurality of wires in the bonding opening bonded to the die and to the wire bonding pads; and

a resin encapsulating the die and covering a top surface of the second mask.

31. (previously presented) The package of claim 30 wherein the die attach area has an outline only slightly larger than that of the die.

32. (previously presented) The package of claim 30 wherein the substrate comprises an organic polymer.

33. (previously presented) The package of claim 30 wherein the adhesive layer comprises a material selected from the group consisting of epoxy, acrylic and polyimide.

Claims 34-36 (canceled)